

Part Number: WP3A10F3BT

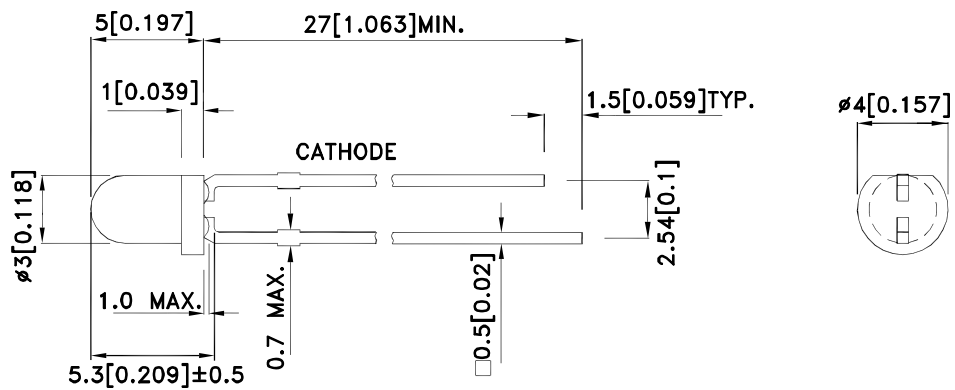
Features

- Mechanically and spectrally matched to the phototransistor.
- RoHS compliant.

Description

F3 Made with Gallium Arsenide Infrared Emitting diodes.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25 (0.01") unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



Selection Guide

Part No.	Dice	Lens Type	Po (mW/sr) [2] @ 20mA		Po (mW/sr) [2] @ 50mA		Viewing Angle [1]
			Min.	Typ.	Min.	Typ.	2θ1/2
WP3A10F3BT	F3 (GaAs)	Blue Transparent	7	35	18	55	50°
			*3	*8	*6	*15	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Radiant Intensity/ luminous flux: +/-15%.
- *Radiant Intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Parameter	P/N	Symbol	Typ.	Max.	Units	Test Conditions
Forward Voltage [1]	F3	V _F	1.2	1.6	V	I _F =20mA
Reverse Current	F3	I _R		10	uA	V _R = 5V
Capacitance	F3	C	90		pF	V _F =0V;f=1MHz
Peak Spectral Wavelength	F3	λ _P	940		nm	I _F =20mA
Spectral Bandwidth	F3	Δλ1/2	50		nm	I _F =20mA

Notes:

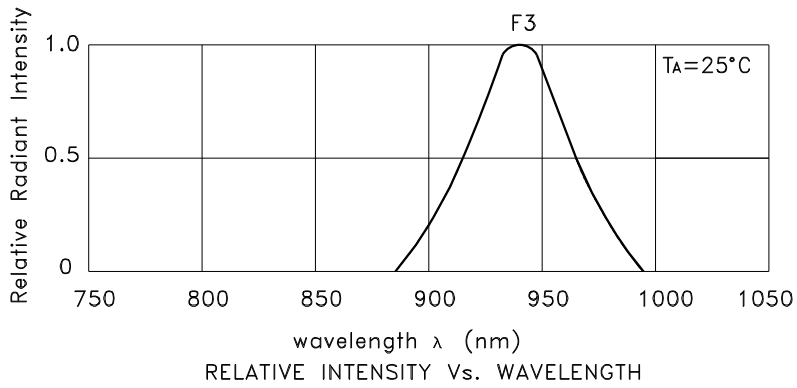
- 1.Forward Voltage: +/-0.1V.
- 2.Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

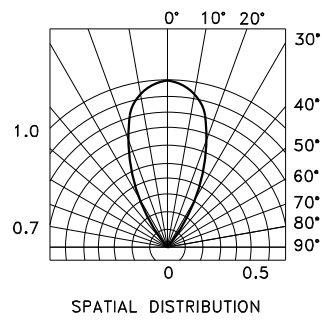
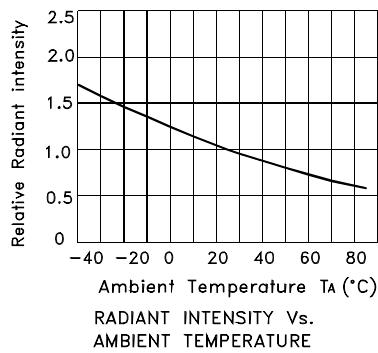
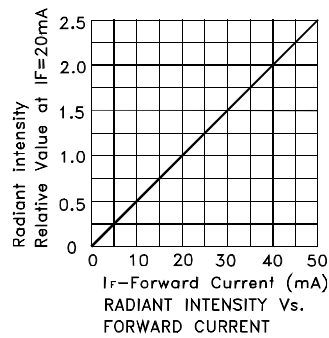
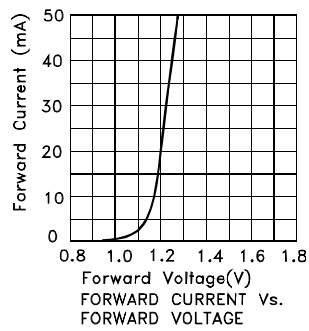
Parameter	Symbol	F3	Units
Power dissipation	P _D	80	mW
DC Forward Current	I _F	50	mA
Peak Forward Current [1]	i _{FS}	1.2	A
Reverse Voltage	V _R	5	V
Operating Temperature	T _A	-40 To +85	°C
Storage Temperature	T _{STG}	-40 To +85	°C
Lead Solder Temperature [2]	260°C For 3 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds		

Notes:

1. 1/100 Duty Cycle, 10μs Pulse Width.
2. 2mm below package base.
3. 5mm below package base.



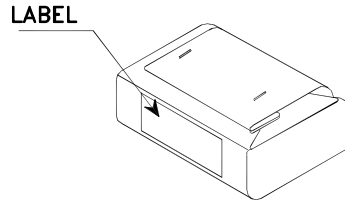
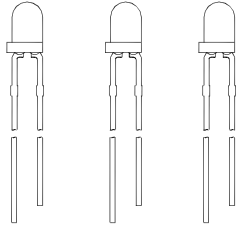
WP3A10F3BT



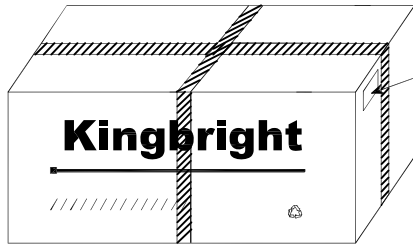
Kingbright

PACKING & LABEL SPECIFICATIONS

WP3A10F3BT

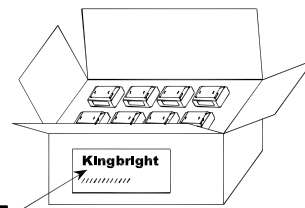


1,000PCS / BAG




56K / 9# BOX

OUTSIDE LABEL



OUTSIDE LABEL

28K / 5# BOX

Kingbright	
P/NO: WP3A10XXX	
QTY: 1,000 pcs	Q.C. Q C XX XX XXXX PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
 <small>XXXXXXXXXXXXXXXXXXXXXXXXXXXX</small>	
RoHS Compliant	

PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



Fig.1

”○” Correct mounting method ”×” Incorrect mounting method

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)

3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



Fig. 2

Fig. 3

Fig. 4

4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)

6. Do not bend the leads more than twice. (Fig. 8)



Fig. 5



Fig. 6



Fig. 7



Fig. 8

7. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



8. The tip of the soldering iron should never touch the lens epoxy.

9. Through-hole LEDs are incompatible with reflow soldering.

10. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.

11. Recommended Wave Soldering Profile for Kingbright Thru-Hole Products



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105°C.
5. No more than once.